

φ0.20ドリル加工事例

φ0.20 Micro-Hole Drilling Performance

用途 半導体パッケージ用、ビルドアップ用内層コア材等 FBGA、BGA、for HDI etc...



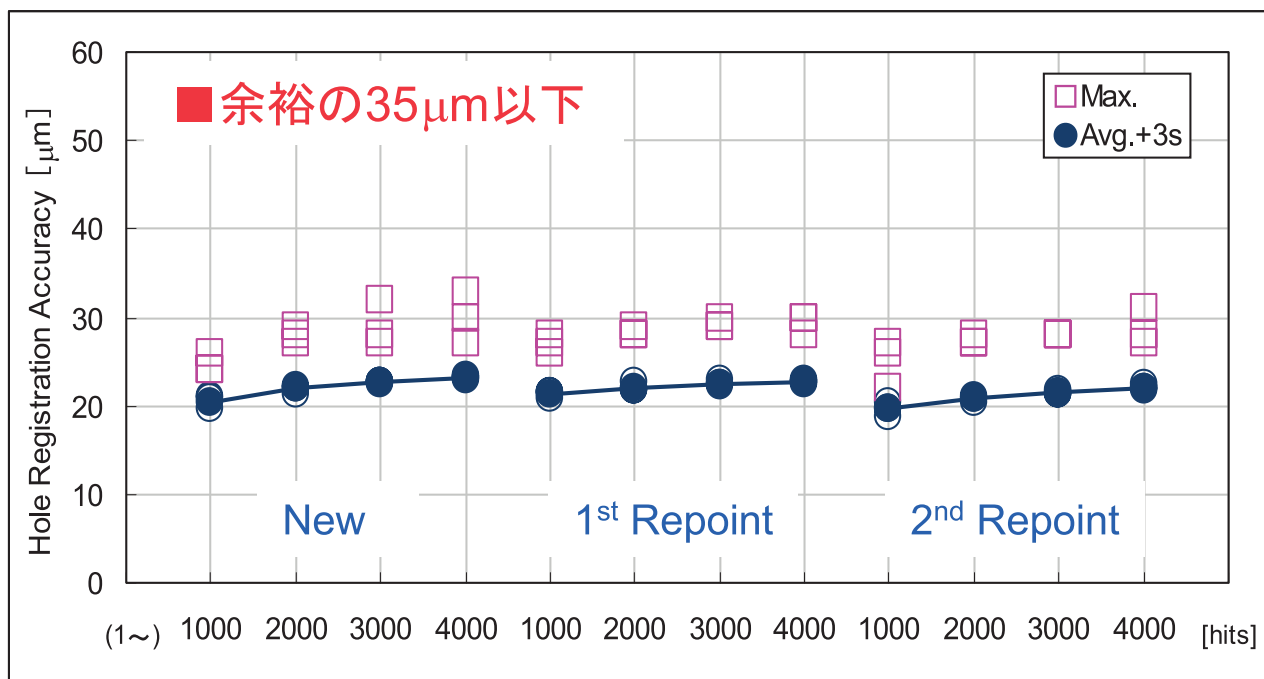
加工条件 [Drilling Condition]

Work Material : MCL-E-679FG(R) t0.8(Double Sided) x 3 stacks

S : 300,000 min⁻¹ F : 4.0m/min f : 13 μm/rev

Set Life : 4,000 hits x Repeint 2 times = Total 12,000 hits

穴位置精度 [Hole Registration Accuracy]



2nd Repeint

(4,000 hits)

内壁粗さ [Hole Wall Quality at 4,000 hits]

